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# Addendum for New QFN Package Migration

This addendum provides the changes to the 98A case outline numbers for products covered in this book. Case outlines were changed because of the migration from gold wire to copper wire in some packages. See the table below for the old (gold wire) package versus the new (copper wire) package.

To view the new drawing, go to [Freescale.com](http://Freescale.com) and search on the new 98A package number for your device.

For more information about QFN package use, see EB806: *Electrical Connection Recommendations for the Exposed Pad on QFN and DFN Packages*.

Part Number	Package Description	Original (gold wire) package document number	Current (copper wire) package document number
MC68HC908JW32	48 QFN	98ARH99048A	98ASA00466D
MC9S08AC16			
MC9S908AC60			
MC9S08AC128			
MC9S08AW60			
MC9S08GB60A			
MC9S08GT16A			
MC9S08JM16			
MC9S08JM60			
MC9S08LL16			
MC9S08QE128			
MC9S08QE32			
MC9S08RG60			
MCF51CN128			
MC9RS08LA8	48 QFN	98ARL10606D	98ASA00466D
MC9S08GT16A	32 QFN	98ARH99035A	98ASA00473D
MC9S908QE32	32 QFN	98ARE10566D	98ASA00473D
MC9S908QE8	32 QFN	98ASA00071D	98ASA00736D
MC9S08JS16	24 QFN	98ARL10608D	98ASA00734D
MC9S08QB8			
MC9S08QG8	24 QFN	98ARL10605D	98ASA00474D
MC9S08SH8	24 QFN	98ARE10714D	98ASA00474D
MC9RS08KB12	24 QFN	98ASA00087D	98ASA00602D
MC9S08QG8	16 QFN	98ARE10614D	98ASA00671D
MC9RS08KB12	8 DFN	98ARL10557D	98ASA00672D
MC9S08QG8			
MC9RS08KA2	6 DFN	98ARL10602D	98ASA00735D

**MC9S08AW60**  
**MC9S08AW48**  
**MC9S08AW32**  
**MC9S08AW16**

Data Sheet

*HCS08*  
*Microcontrollers*

MC9S08AW60  
Rev 2  
12/2006

[freescale.com](http://freescale.com)



# MC9S08AW60 Features

## 8-Bit HCS08 Central Processor Unit (CPU)

- 40-MHz HCS08 CPU (central processor unit)
- 20-MHz internal bus frequency
- HC08 instruction set with added BGND instruction
- Single-wire background debug mode interface
- Breakpoint capability to allow single breakpoint setting during in-circuit debugging (plus two more breakpoints in on-chip debug module)
- On-chip real-time in-circuit emulation (ICE) with two comparators (plus one in BDM), nine trigger modes, and on-chip bus capture buffer. Typically shows approximately 50 instructions before or after the trigger point.
- Support for up to 32 interrupt/reset sources

## Memory Options

- Up to 60 KB of on-chip in-circuit programmable FLASH memory with block protection and security options
- Up to 2 KB of on-chip RAM

## Clock Source Options

- Clock source options include crystal, resonator, external clock, or internally generated clock with precision NVM trimming

## System Protection

- Optional computer operating properly (COP) reset
- Low-voltage detection with reset or interrupt
- Illegal opcode detection with reset
- Illegal address detection with reset (some devices don't have illegal addresses)

## Power-Saving Modes

- Wait plus two stops

## Peripherals

- **ADC** — Up to 16-channel, 10-bit analog-to-digital converter with automatic compare function
- **SCI** — Two serial communications interface modules with optional 13-bit break
- **SPI** — Serial peripheral interface module

- **IIC** — Inter-integrated circuit bus module to operate at up to 100 kbps with maximum bus loading; capable of higher baud rates with reduced loading
- **Timers** — One 2-channel and one 6-channel 16-bit timer/pulse-width modulator (TPM) module: Selectable input capture, output compare, and edge-aligned PWM capability on each channel. Each timer module may be configured for buffered, centered PWM (CPWM) on all channels
- **KBI** — Up to 8-pin keyboard interrupt module

## Input/Output

- Up to 54 general-purpose input/output (I/O) pins
- Software-selectable pullups on ports when used as inputs
- Software-selectable slew rate control on ports when used as outputs
- Software-selectable drive strength on ports when used as outputs
- Master reset pin and power-on reset (POR)
- Internal pullup on  $\overline{\text{RESET}}$ , IRQ, and BKGD/MS pins to reduce customer system cost

## Package Options

### MC9S08AW60/48/32

- 64-pin quad flat package (QFP)
- 64-pin low-profile quad flat package (LQFP)
- 48-pin low-profile quad flat package (QFN)
- 44-pin low-profile quad flat package (LQFP)

### MC9S08AW16

- 48-pin low-profile quad flat package (QFN)
- 44-pin low-profile quad flat package (LQFP)



# MC9S08AW60 Data Sheet

Covers: MC9S08AW60

MC9S08AW48

MC9S08AW32

MC9S08AW16

MC9S08AW60

Rev 2

12/2006





## Revision History

To provide the most up-to-date information, the revision of our documents on the World Wide Web will be the most current. Your printed copy may be an earlier revision. To verify you have the latest information available, refer to:

<http://freescale.com/>

The following revision history table summarizes changes contained in this document. For your convenience, the page number designators have been linked to the appropriate location.

Revision Number	Revision Date	Description of Changes
1	1/2006	Initial external release.
2	12/2006	Includes KBI block changes; new $V_{OL}$ / $I_{OL}$ figures; $R_{IDD}$ spec changes; SC part numbers with ICG trim modifications; addition of Temp Sensor to ADC. Resolved the stop IDD issues, added RTI figure, bandgap information, and incorporated electricals edits and any ProjectSync issues.

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# Chapter 1 Introduction

## 1.1 Overview

The MC9S08AW60, MC9S08AW48, MC9S08AW32, and MC9S08AW16 are members of the low-cost, high-performance HCS08 family of 8-bit microcontroller units (MCUs). All MCUs in the family use the enhanced HCS08 core and are available with a variety of modules, memory sizes, memory types, and package types. Refer to [Table 1-1](#) for memory sizes and package types.

[Table 1-2](#) summarizes the peripheral availability per package type for the devices available in the MC9S08AW60 Series.

**Table 1-1. Devices in the MC9S08AW60 Series**

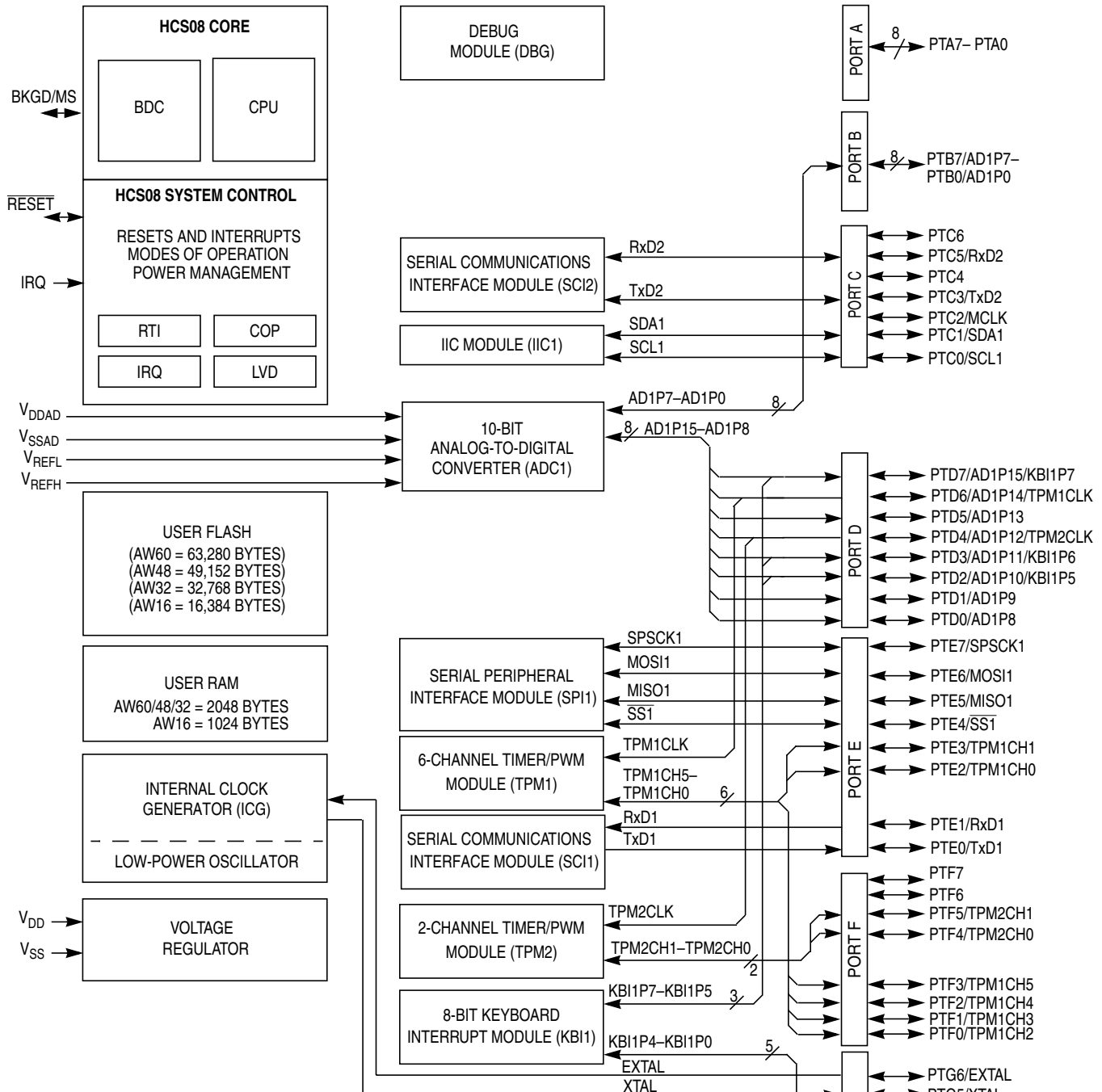
Device	FLASH	RAM	Package
MC9S08AW60	63,280	2048	64 QFP
MC9S08AW48	49,152		64 LQFP
MC9S08AW32	32,768		48 QFN 44 LQFP
MC9S08AW16	16,384	1024	48 QFN 44 LQFP

**Table 1-2. Peripherals Available per Package Type**

Feature	Package Options		
	64-pin	48-pin	44-pin
ADC	16-channel	8-channel	8-channel
IIC	yes	yes	yes
IRQ	yes	yes	yes
KB11	8	7	6
SCI1	yes	yes	yes
SCI2	yes	yes	yes
SPI1	yes	yes	yes
TPM1	6-channel	4-channel	4-channel
TPM1CLK	yes	no	no
TPM2	2-channel	2-channel	2-channel
TPM2CLK	yes	no	no
I/O pins	54	38	34

## 1.2 MCU Block Diagrams

The block diagram shows the structure of the MC9S08AW60 Series.



**NOTES:**

1. Port pins are software configurable with pullup device if input port.
2. Pin contains software-configurable pullup/pulldown device if IRQ is enabled (IRQPE = 1). Pulldown is enabled if rising edge detect is selected (IRQEDG = 1)
3. IRQ does not have a clamp diode to V<sub>DD</sub>. IRQ should not be driven above V<sub>DD</sub>.
4. Pin contains integrated pullup device.
5. Pins PTD7, PTD3, PTD2, and PTG4 contain both pullup and pulldown devices. Pulldown enabled when KBI is enabled (KBIPE<sub>n</sub> = 1) and rising edge is selected (KBEDG<sub>n</sub> = 1).

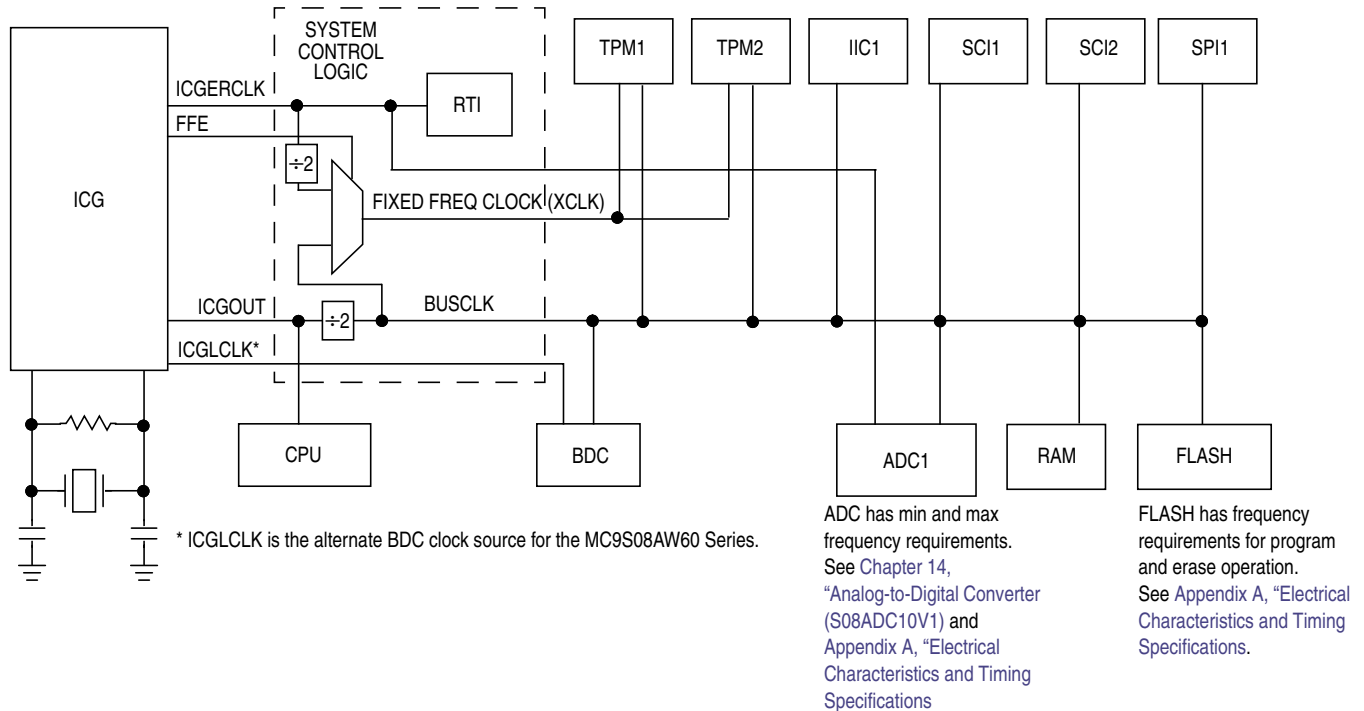
**Figure 1-1. MC9S08AW60 Series Block Diagram**

Table 1-3 lists the functional versions of the on-chip modules.

**Table 1-3. Versions of On-Chip Modules**

Module	Version
Analog-to-Digital Converter (S08ADC10)	1
Internal Clock Generator (S08ICG)	4
Inter-Integrated Circuit (S08IIC)	1
Keyboard Interrupt (S08KBI)	1
Serial Communications Interface (S08SCI)	2
Serial Peripheral Interface (S08SPI)	3
Timer Pulse-Width Modulator (S08TPM)	2
Central Processing Unit (S08CPU)	2
Debug Module (DBG)	2

### 1.3 System Clock Distribution



**Figure 1-2. System Clock Distribution Diagram**

Some of the modules inside the MCU have clock source choices. Figure 1-2 shows a simplified clock connection diagram. The ICG supplies the clock sources:

- ICGOUT is an output of the ICG module. It is one of the following:
  - The external crystal oscillator
  - An external clock source



- The output of the digitally-controlled oscillator (DCO) in the frequency-locked loop sub-module
- Control bits inside the ICG determine which source is connected.
- FFE is a control signal generated inside the ICG. If the frequency of ICGOUT  $> 4 \times$  the frequency of ICGERCLK, this signal is a logic 1 and the fixed-frequency clock will be ICGERCLK/2. Otherwise the fixed-frequency clock will be BUSCLK.
- ICGLCLK — Development tools can select this internal self-clocked source (~ 8 MHz) to speed up BDC communications in systems where the bus clock is slow.
- ICGERCLK — External reference clock can be selected as the real-time interrupt clock source. Can also be used as the ALTCLK input to the ADC module.

## **Chapter 2**

# **Pins and Connections**

### **2.1 Introduction**

This chapter describes signals that connect to package pins. It includes a pinout diagram, a table of signal properties, and detailed discussion of signals.